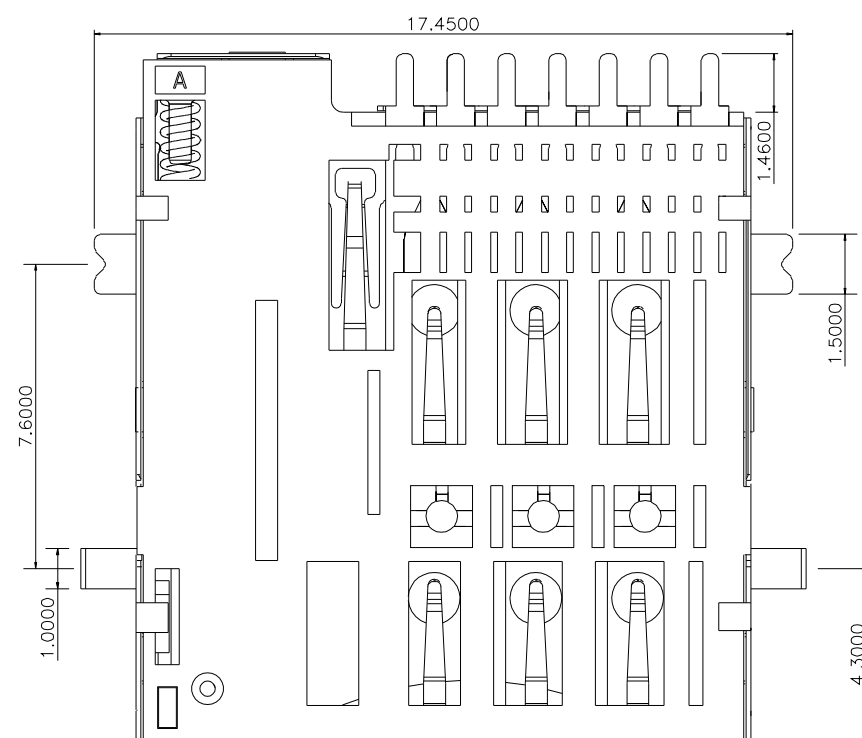
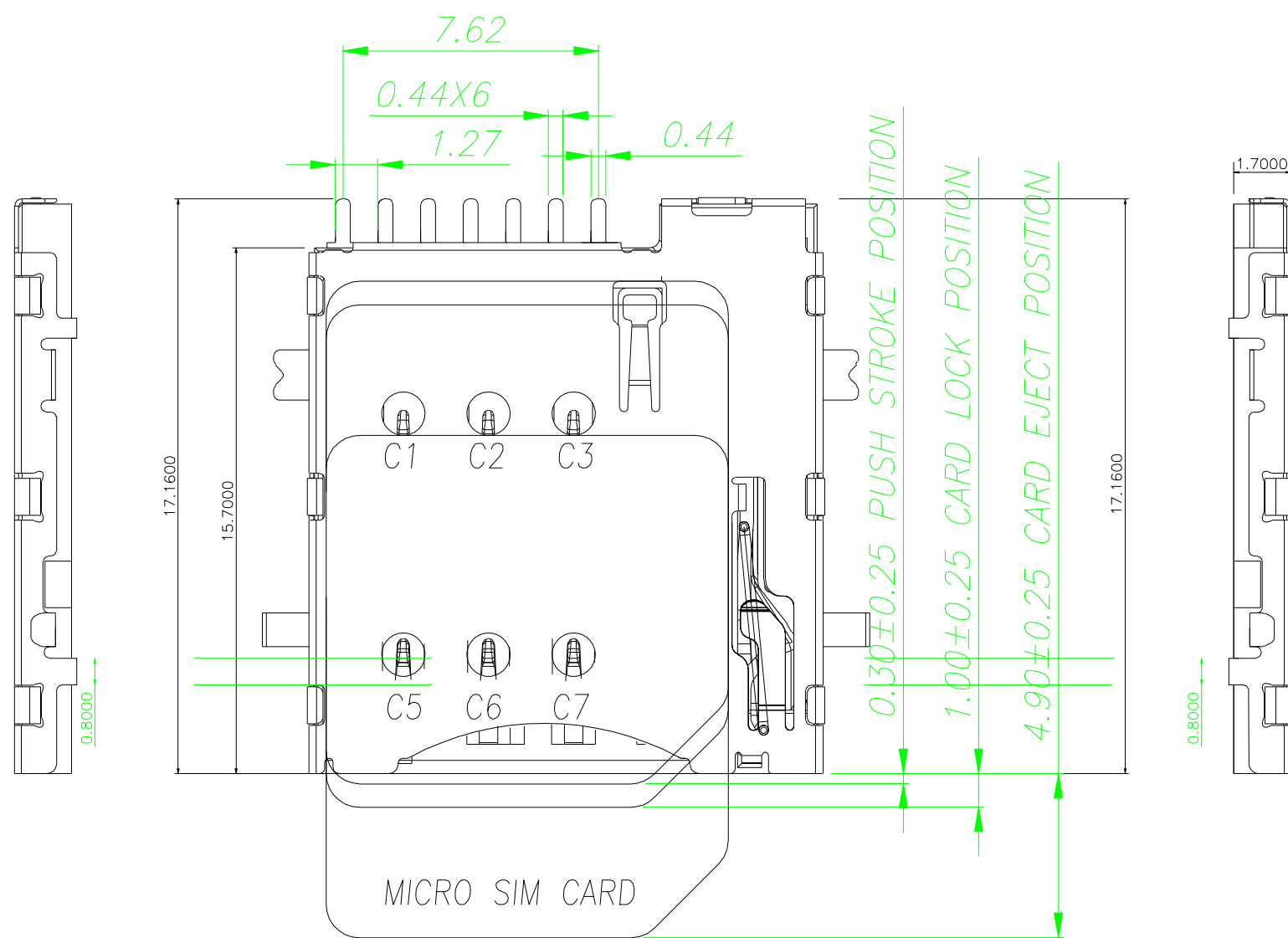
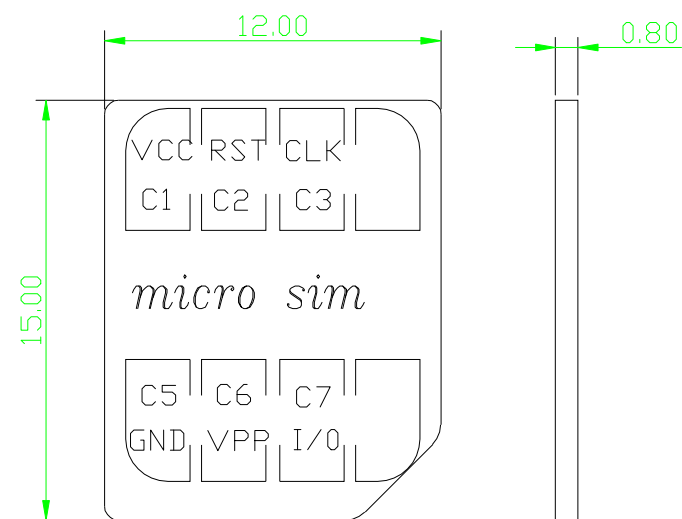
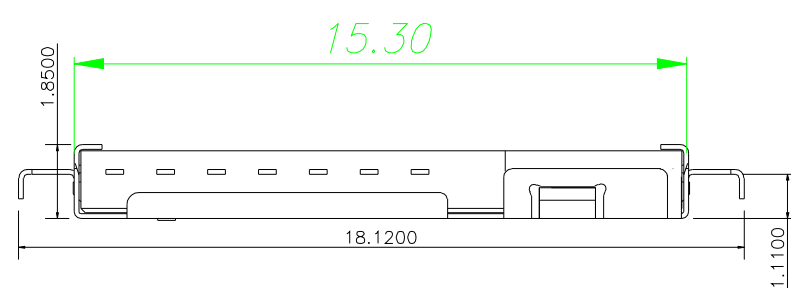


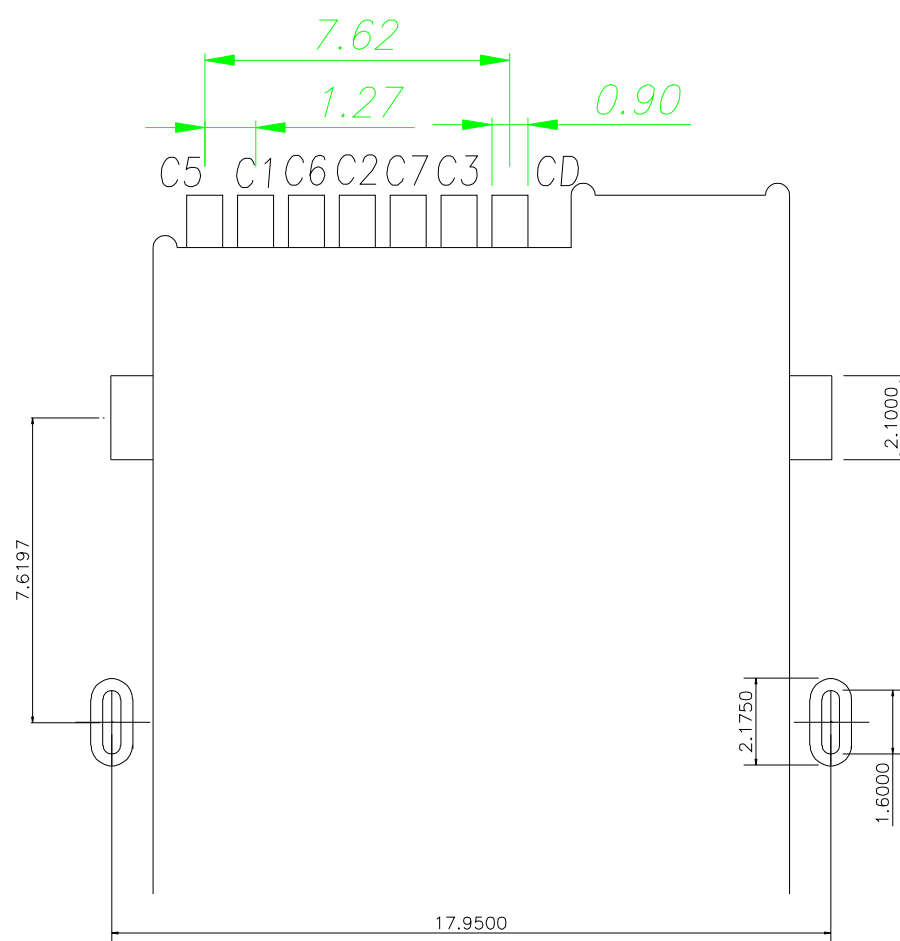
| REV. | EC# | DESCRIPTION | DATE | DRAWING | CHECKED | APPROVED |
|------|-----|-------------|----------|---------|---------|-----------|
| A | | NEW RELEASE | 20140903 | wen | | changyong |
| A1 | | 更改外壳焊脚间距和宽度 | 20151022 | wen | | changyong |



| SIM pin Assignment | |
|--------------------|------|
| PIN# | Name |
| C1 | VCC |
| C2 | RST |
| C3 | CLK |
| C5 | GND |
| C6 | VPP |
| C7 | I/O |



MICRO SIM CARD



NOTES:

MATERIAL:

Insulator: High Temperature Thermoplastic, UL 94V-0.
 Contact: Copper Alloy
 Shell: STAINLESS

PLATING :

TERMINAL:
 CONTACT AREA: GOLD FLASH.
 SOLDER AREA: MATTE TIN PLATED.
 UNDER PLATE: NICKEL.
 SHELL: NICKEL OVER ALL.
 SOLDER AREA: GOLD FLASH.

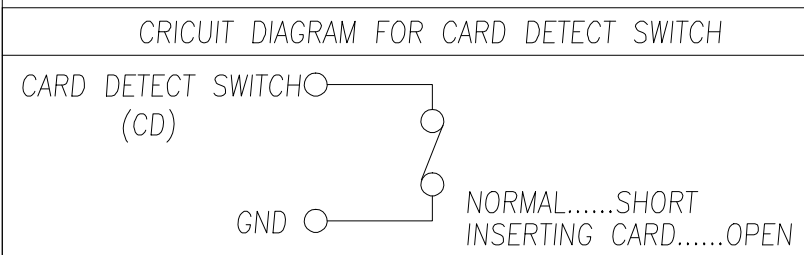
Electrical:

Current Rating :0.5mA max.
 Voltage Rating :50V DC MAX
 Ambient Temperature Range :-20° C~+85° C
 Storage Temperature Range :-40° C~+70° C
 Ambient Humidity Range :95% R.H. Max.
 Contact Resistance:100mΩmax.
 Insulation Resistance:1000MΩmin./250V DC
 Dielectric Withstanding Voltage:500V AC
 Mating Cycles:5,000 Insertions
 Temperature: 260° C ±5°

■ CIRCUIT TRACE KEEP OUT AREA
 ■ SMT SOLDER AREA

THERE SHOULD NOT BE ANY CIRCUITRIES IN THE LAYOUT SPACE OF THE PRODUCTS.

RECOMMENDED PCB LAYOUT
 GENERAL TOLERANCE ±0.05



| MILLIMETERS | INCH | UNITS |
|-------------|---------|-----------|
| X.° ± 2' | X.° ± | MM |
| .X ± 0.30 | .XX ± | MAT'L |
| .XX ± 0.25 | .XXX ± | SEE NOTES |
| .XXX ± 0.15 | .XXXX ± | FINISH |
| | | SEE NOTES |
| | | QTY |
| | | SEE NOTES |

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深圳市迈睿康科技有限公司

| | | |
|--------------|-------------------------------|------|
| PART NUMBER: | TITLE: | |
| APPD: wcy | MICRO-SIM 卡座PUSH/PUSH 7PIN 沉板 | |
| CHKD: | DWG NO.: | |
| DR: | MRK-SM09-135-0021 | |
| SCALE | SHEET | REV. |
| 1:1 | 1/2 | A1 |